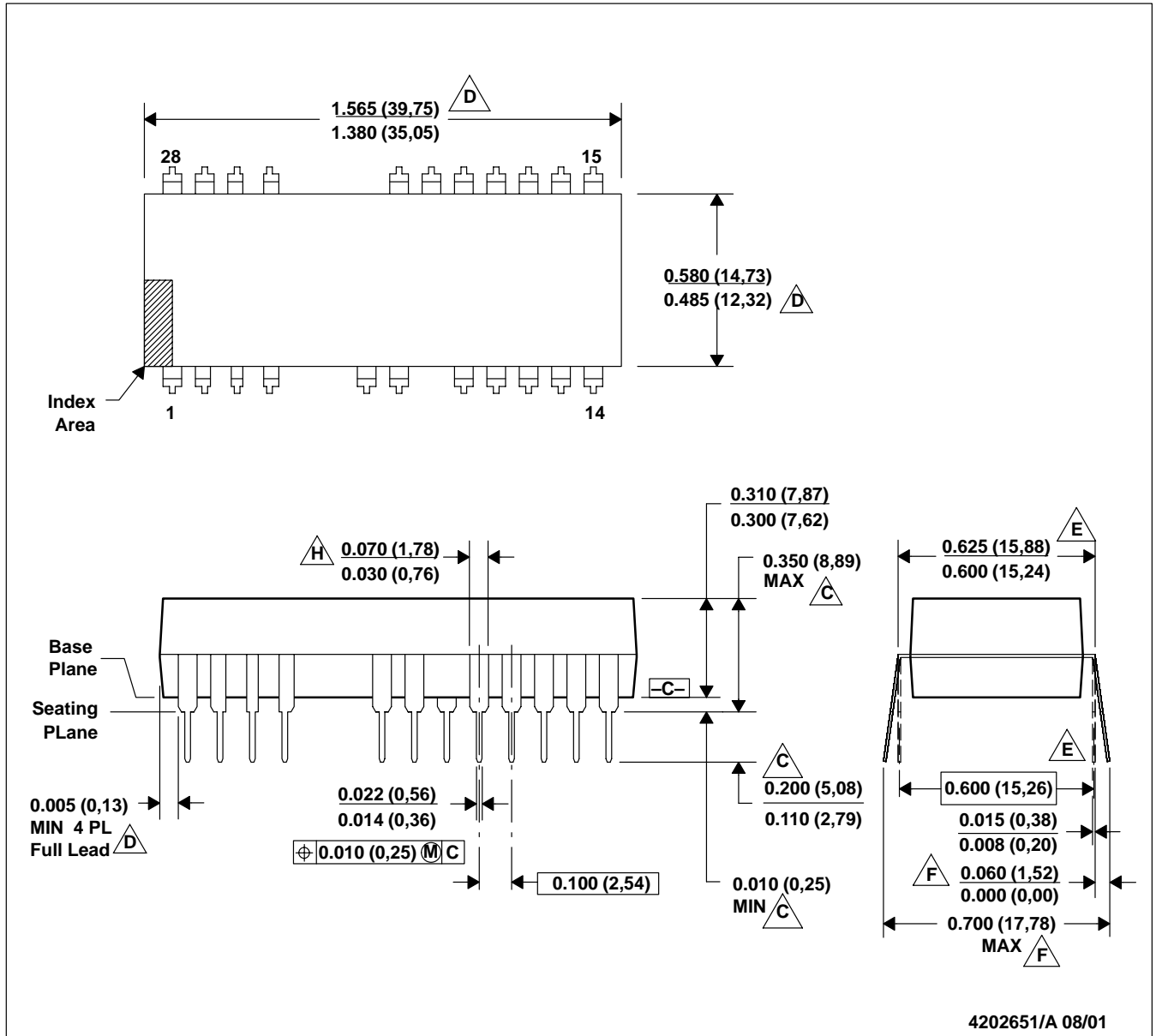


NVM (R-PDIP-T22/28)

PLASTIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Dimensions are measured with the package seated in JEDEC seating plane gauge GS-3.
 D. Dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 (0,25).
 E. Dimensions measured with the leads constrained to be perpendicular to Datum C.
 F. Dimensions are measured at the lead tips with the leads unconstrained.
 G. Pointed or rounded lead tips are preferred to ease insertion.
 H. Maximum dimension does not include dambar protrusions. Dambar protrusions shall not exceed 0.005 (0,13).
 I. Lead shoulder dimension for leads 2, 3, 4, 25, 26 less than nominal to maintain specified lead spacing.
 J. A visual index feature must be located within the cross-hatched area.
 K. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

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